

A High Precision Low Dropout Regulator with Nested Feedback Loops

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Abstract—A high precision low dropout regulator (LDO) with nested feedback loops is proposed in this paper. By nesting a zero-tracking compensation loop inside of the negative feedback loop comprising an Error Amplifier, the independence of off-chip capacitor and ESR is ensured for different load currents and operating voltages. Therefore, in low I_{ddq} or low voltage scenarios, the total error of the output voltage caused by line and load variations is less than $\pm 3\%$ according to on-silicon measurement results.

Index Terms—Low dropout, low noise, and LDO

I. INTRODUCTION

The LDO (low-dropout) regulator is generally utilized to translate a voltage level or provide a stable output voltage, which has been considered as one of the important components for the power management of wireless applications, e.g., cellular phones, hand-held computers, and particularly implanted wireless biomedical chips [1]. Traditional linear LDO regulators usually consist of a two-stage error amplifier, a power output stage and a negative feedback loop. However, since the stability and accuracy of the regulated output voltage is the most critical factor in many field applications such as biomedical chips, traditional designs suffer from poor efficiency as the difference between the input and output voltages is increased [2]. To attain a fast transient response and an accurate output voltage, several prior LDO regulators were proposed to use high gain amplifiers with either a cascade or cascode technology. It results in the stability problem due to the appearance of inherent three poles. Besides, the varying load current also affects the stability [3] - [5]. Thus, a frequency compensation technique to ensure the stability of the LDO regulator was proposed to resolve this problem [3] - [12]. Traditionally, the off-chip capacitor and its ESR (equivalent series resistor) are designed to move the zero around to achieve a pole-zero cancelation and keep the phase margin larger than zero degree. However, the off-chip capacitor increases the area of the printed-circuit board (PCB) and the value of the ESR might drift owing to the variation of the temperature and different materials. Therefore, the off-chip capacitor scheme is not acceptable in many applications demanding high precision. In this work, a new compensation architecture independent of the off-chip capacitor and its ESR is presented to enhance the LDO regulator's performance regarding the transient response and the noise rejection. Besides, a novel bandgap reference

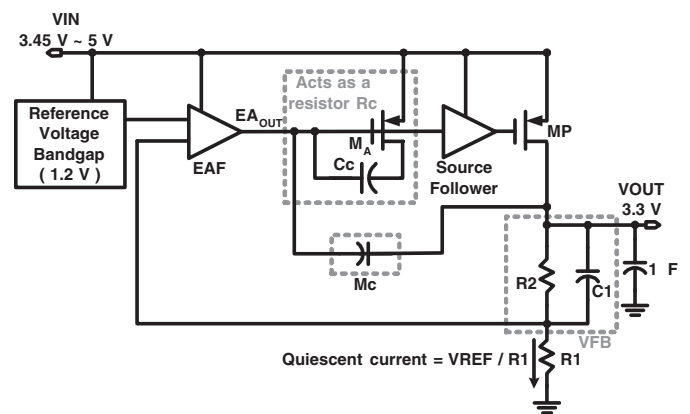


Fig. 1. Architecture of the proposed low noise low dropout regulator.

integrated with an error amplifier in a feedback loop is proposed to achieve the high precision of LDO.

II. CIRCUIT DESIGN

Fig.1 shows the block diagram of the proposed LDO which is composed of a Reference Voltage Bandgap, an Error Amplifier, a Source Follower, a Power MOS (MP), a voltage divider composed of R1 and R2, a variable resistance R_c.

A. Bandgap Reference

To generate a stable voltage against process and temperature variations, a novel bandgap reference circuit is adopted. To enhance the capability against the supply voltage variation and the noise coupling from the substrate, a feedback loop with an error amplifier (EAB) is used as shown in Fig. 2. Assuming the gain of the EAB is very large, V_x and V_y are approximately equal, where V_y and V_x are the voltages at the inverting and noninverting input terminals of EAB, respectively. In Fig. 2, transistors M1 and M2 are both operated in saturation region. Taking channel-length modulation into consideration, the drain currents of M1 and M2, I_1 and I_2 , can be written as

$$I_1 = \frac{\beta_1}{2}(V_{GS1} - V_{TH1})^2(1 + \lambda V_{DS1}) \quad (1)$$

$$I_2 = \frac{\beta_2}{2}(V_{GS2} - V_{TH2})^2(1 + \lambda V_{DS2}) \quad (2)$$

where V_{GS1} and V_{GS2} are the gate to source voltage of M1 and M2, respectively, V_{TH1} and V_{TH2} are the threshold voltage of M1 and M2, respectively, λ is the channel-length modulation coefficient, V_{DS1} and V_{DS2} are the drain to source voltage of M1 and M2, respectively, β_1 and β_2 represent the device parameters of M1 and M2, respectively. Given that $I_1 = I_2$, $V_{GS1} = V_{GS2}$, $V_{DS1} = V_{DS2}$, we can have

$$V_{GS1} + V_{BE1} = V_{GS2} + I_1 \times R_3 + V_{BE2} \quad (3)$$

Eqn. (3) can be rewritten as

$$\begin{aligned} I_2 &= \frac{V_{BE1} - V_{BE2} + V_{GS1} - V_{GS2}}{R_3} \\ &= \frac{V_{BE1} - V_{BE2}}{R_3} = I_3 \end{aligned} \quad (4)$$

Since $V_{BE} = V_T \times \ln\left(\frac{I_c}{I_s}\right)$, and the size of Q2 and Q3 are both the n times of that of Q1, I3 can be expressed as:

$$I_3 = \frac{V_T \times \ln(n)}{R_3} \quad (5)$$

Then, the sensitivity of I3 versus temperature can be derived as

$$\frac{\partial I_3}{\partial T} = \frac{K}{q} \times \frac{\ln(n)}{R_3} \quad (6)$$

Since $I_s = cT^{4+m} \exp\left(\frac{-E_g}{KT}\right)$, where c and m are constants, the sensitivity of V_{BE} versus temperature can be derived as

$$\frac{\partial V_{BE}}{\partial T} = \frac{V_{BE} - (4+m)V_T - \frac{E_g}{q}}{T} = -1.5 \text{ (mV/K)} \quad (7)$$

where $T=300^\circ\text{K}$, $V_{BE}=0.75\text{ V}$ in Eqn. (7).

In Fig. 2, $V_{REF} = I_3 \times R_4 + V_{BE3}$. Hence, the sensitivity of V_{REF} versus temperature can be derived as

$$\frac{\partial V_{REF}}{\partial T} = \frac{R_4}{R_3} \times \frac{K}{T} \ln(n) + \frac{V_{BE} - (4+m)V_T - \frac{E_g}{q}}{T} \quad (8)$$

Thus, the sensitivity of V_{REF} can be eliminated by adjusting the value of R_4 to generate a stable reference voltage.

B. Source Follower

Source Follower is used to drive the large capacitance load and the small resistance load. The $E_{A_{OUT}}$ is fed into the Source Follower to drive MP in the saturation region, where V_{B4} is a bias voltage connected to EAF, as shown in Fig. 3.

C. Error Amplifier

Speed and gain always determine the performance of the LDO, and the speed of the LDO are mainly determined by the error amplifier, i.e., EAF, in Fig. 1. In order to reduce the the noise from V_{IN} , EAF is implemented with a folded cascode structure, as shown in Fig. 3, where V_{B4} is a voltage bias connected to the following Source Follower. Moreover, the cascode structure can enlarge the gain to provide a precise output voltage of LDO.

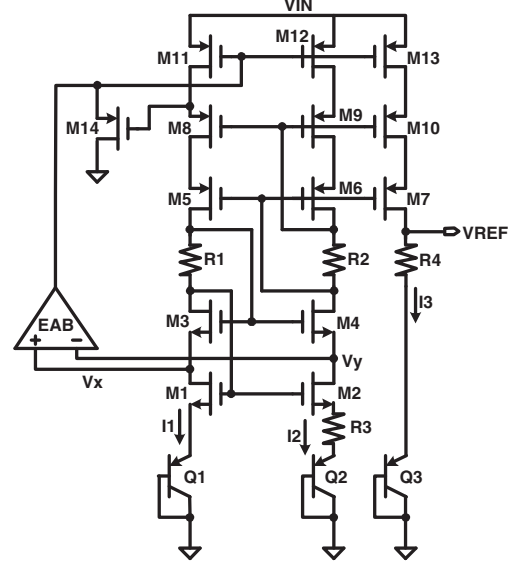


Fig. 2. The schematic of bandgap reference.

D. Frequency Compensation

In a negative feedback system, the stability is always a critical issue. To ensure the stability of the system, the phase margin of the open loop gain should be carefully designed. In traditional LDO architectures, the phase margin is dominated by the load. Therefore, two frequency compensated methods are adopted to keep our LDO apart from load capacitor and its ESR.

1) *Zero-tracking compensation*: As shown in Fig. 1, the PMOS, M_A , is biased in the triode region to act as a variable resistance. Its resistance is varied with the voltage at V_{OUT} , which is the load voltage. Therefore, the zero is varied with the dominant pole to avoid the bandwidth of the LDO from decreasing. Meanwhile, the phase margin is also compensated.

2) *Nested Miller compensation*: A small Miller capacitor, M_c , is inserted on the feedback path to the gate of M_A , as shown in Fig. 1. Besides, the feedback voltage divider composed of R_1 and R_2 are connected with C_1 in parallel to generate a extra zero and pole. When the pole's frequency equals $(1+R_2/R_1)k$ times of the zero's frequency, the noise of the system can be eliminated, where k is the experimental constant. According to our measurement in Section III, the frequency of the pole is about 2.75 times of the zero's frequency.

III. SIMULATION AND MEASUREMENT

A. Simulation of the Bandgap Reference

The low noise LDO is designed and fabricated in a $0.18\ \mu\text{m}$ standard CMOS process. The bandgap reference with a compensated Error Amplifier has been simulated given the temperature from $-40\ ^\circ\text{C}$ to $120\ ^\circ\text{C}$. as shown in Fig. 4. V_{REF} has a variation of $\pm 1\ \text{mV}$ from the mean value $1.204\ \text{V}$ given different process corners. A stable V_{REF} is obtained given different V_{IN} from $3\ \text{V}$ to $5\ \text{V}$, as shown in Fig. 5.

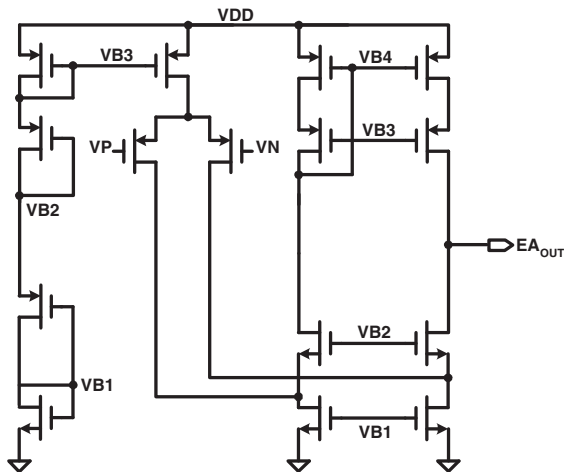


Fig. 3. Error amplifier (EAF).

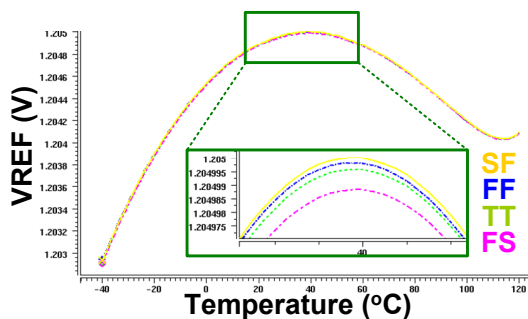


Fig. 4. Bandgap reference simulations given different process corners.

B. Measurement Results for the Proposed LDO

Fig. 6 shows the die photo of the proposed circuit. The measured environment is composed of an digital oscilloscope, a function generator, and a power supply. The smallest dropout of the LDO is 0.018 V while the output current is 165 mA, the output load is 4.7 μ F and 20 Ω in parallel. Fig. 7 shows the transient response of LDO in the line regulation measurement. When VIN is switching switching from 3.45 V to 5 V, VOUT is stable with a settling time less than 36.55 μ s and a line regulation of 0.012%. When load regulation is measured, the test configuration with R5 = 1K Ω and R6 = 14 Ω in Fig. 8 is used, where R5 and R6 are load resistances. Fig. 9 shows the measured transient response of LDO at VIN = 3.3 V with the output current switching from 120 mA to 0 mA. When M0 is turned off, VOUT is stabilized with a settling time less than 42.54 μ s and a load regulation of 0.005%. Fig. 10 and Fig. 11 shows the measured PSRR when VIN is at 30.08 kHz and 3.08 kHz, respectively. The quiescent current, Iddq, is 50 μ A with a load current = 240 mA. The performance comparison of LDOs is shown in Table I. Our design has the edge of minimal line regulation, load regulation and dropout voltage.

IV. CONCLUSION

In this paper, a novel bandgap reference with a compensated error amplifier for high precision LDO is proposed. This

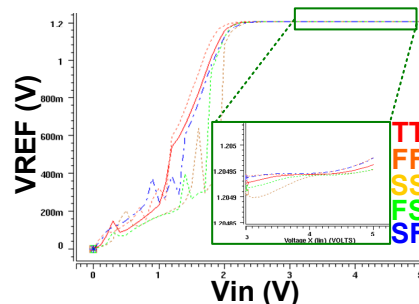


Fig. 5. VREF is stable given different VIN from 3 V to 5 V.

design is independent of the off-chip capacitor and its ESR. The measurement results justify its high precision with line regulation=0.012% and load regulation=0.005%. Moreover, the PSRR stays over 50 dB even if the operating frequency is up to 3.08 kHz.

V. ACKNOWLEDGMENT

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REFERENCES

- [1] R. J. Baker, H. W. Li, and D. E. Boyce, "CMOS circuit design, layout, and simulation," in *Proc. 15th Int. Conf. on Electronics, Circuits and Systems*, pp. 1047-1050, Aug. 2008.
- [2] K. N. Leung and Philip K. T. Mok, "A capacitor-free CMOS low-dropout regulator with damping-factor-control frequency compensation," *IEEE J. of Solid-State Circuits*, vol. 38, no. 10, pp. 1697-1702, Oct. 2003.
- [3] S. Hui, W. Xiaobo, and Y. Xiaolang, "A precise bandgap reference with high PSRR," in *Proc. IEEE Int. Conf. on Electron Devices and Solid-State Circuits*, pp.267-270, Dec. 2005.
- [4] H.-C. Lin, H.-H. Wu, and T.-Y. Chang, "An active-frequency compensation scheme for CMOS low-dropout regulators with transient-response improvement," *IEEE Tran. on Circuits and Systems II: Express Briefs*, vol. 55, no. 9, pp. 853-857, Sept. 2008.
- [5] M. Al-Shyoukh, H. Lee, and R. Perez, "A transient-enhanced low-quiescent current low-dropout regulator with buffer impedance attenuation," *IEEE J. Solid-State Circuits*, vol. 42, no. 8, pp. 1732-1742, Aug. 2007.
- [6] S. Heng and C.-K. Pham, "Improvement of LDO's PSRR deteriorated by reducing power consumption : implementation and experimental results," in *Proc. IEEE Int. Conf. on IC Design and Technology*, pp. 11-15, May 2009.
- [7] W.-J. and S.-I. Liu, "A sub-1V low-dropout regulator with an on-chip voltage reference," in *Proc. IEEE Asian. Solid-state Circuits Conf.*, pp. 165-168, Nov. 2008.
- [8] V. Majidzadeh, A. Schmid, and Y. Leblebici, "A fully on-chip LDO voltage regulator for remotely powered cortical implants," in *Proc. IEEE ESSCIRC*, pp. 424 - 427, Sept. 2009.
- [9] V. Gupta and G. A. Rincon-Mora, "A 5mA 0.6 μ m CMOS miller-compensated LDO regulator with -27dB worst-case power-supply rejection using 60pF of on-chip capacitance," in *Dig. Tech. Papers IEEE Int. Solid-State Circuits Conf.*, pp. 520-521, 2007.

TABLE I
PERFORMANCE CAPARISON OF LDO

	[8]	[4]	[5]	[6]	Ours
process (μm)	0.18	0.18	0.35	0.18	0.18
year	2009	2008	2007	2009	2010
Line regulation (%)	0.024	N/A	N/A	0.231	0.012
Load regulation (%)	0.7	N/A	N/A	0.101	0.005
Dropout (V)	0.3	N/A	0.2	0.541	0.018
ESR zero required	Yes	No	No	Yes	No
I _{ddq} (mA)	0.028	0.027	0.02	0.035	0.05
I _{Lmax} (mA)	N/A	150	200	150	240

- [10] R. K. Dokania and G. A. Rincon-Mora, "Cancellation of load regulation in low drop-out regulators," *Electronics Letters*, pp. 1300-1302, 2002.
- [11] C.-C. Wang, C.-C. Huang, T.-J. Lee, and U.-F. Chio, "A linear LDO regulator with modified NMCF frequency compensation independent of off-chip capactor and ESR" in *Proc. IEEE Asia Pacific Conf. on Circuits and Systems*, pp. 880-883, Nov. 2006.
- [12] C. Stanescu, "Buffer stage foe fast response LDO," in *Proc. International Semiconductor Conf.*, vol. 2, pp. 357-360, Sept. 2003.

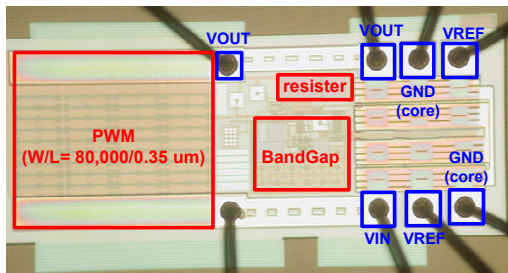


Fig. 6. Die photo of the proposed LDO.

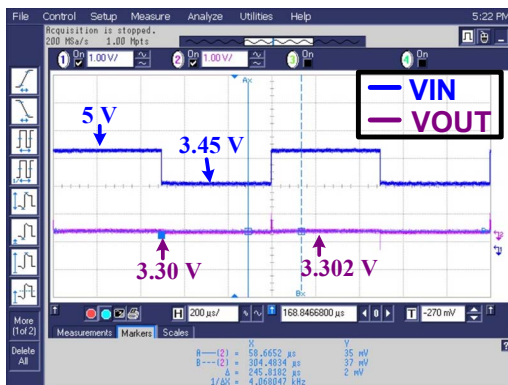


Fig. 7. Measured line regulation of proposed LDO.

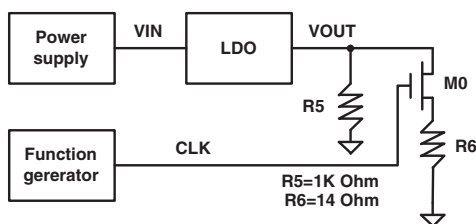


Fig. 8. Measured architecture for LDO Load regulation.

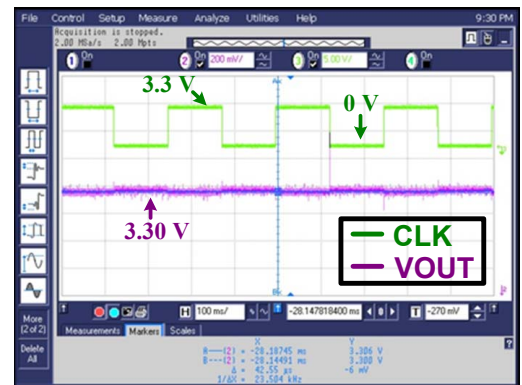


Fig. 9. Measured Load regulation of proposed LDO.

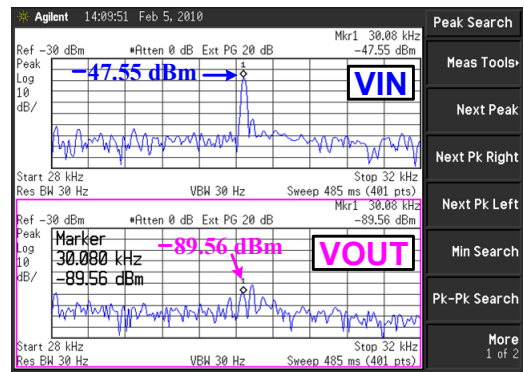


Fig. 10. Measured PSRR at VIN = 30.08 kHz.

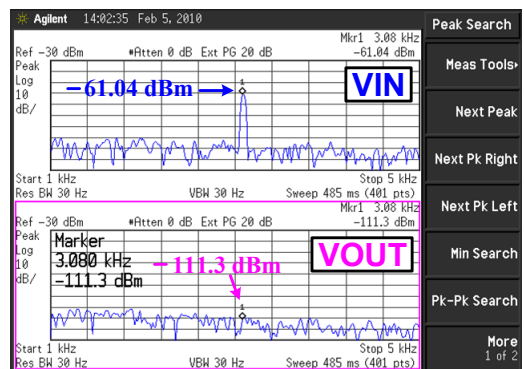


Fig. 11. Measured PSRR at VIN = 3.08 kHz.